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(54) **RFID TAG INLAY**
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(**) Term: **15 Years**
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(52) **U.S. Cl.**
USPC **D14/230**

(58) **Field of Classification Search**
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CPC H01Q 7/00; H01Q 13/10; H01Q 9/285; H01Q 19/30; H01Q 19/12; H01Q 1/38; H01Q 1/36; H01Q 2/0027; H01Q 1/48; H01Q 9/045; H01Q 1/243; H04B 1/0475; H04B 1/034; H05K 11/00

See application file for complete search history.

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Primary Examiner — John Windmuller

(57) **CLAIM**

The ornamental design for an RFID tag inlay, as shown and described.

DESCRIPTION

The sole FIGURE is a front elevational view of an RFID tag inlay showing my new design. The solid black areas constitute the entirety of the claimed design. All elements of the claimed design are flat and coplanar.

1 Claim, 1 Drawing Sheet



